

FIG. 1  
(PRIOR ART)

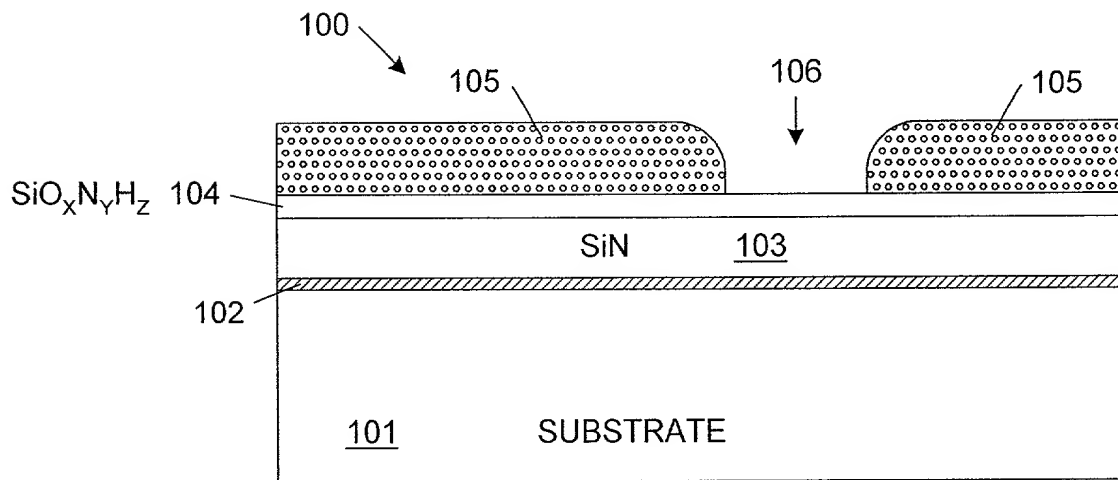


FIG. 2

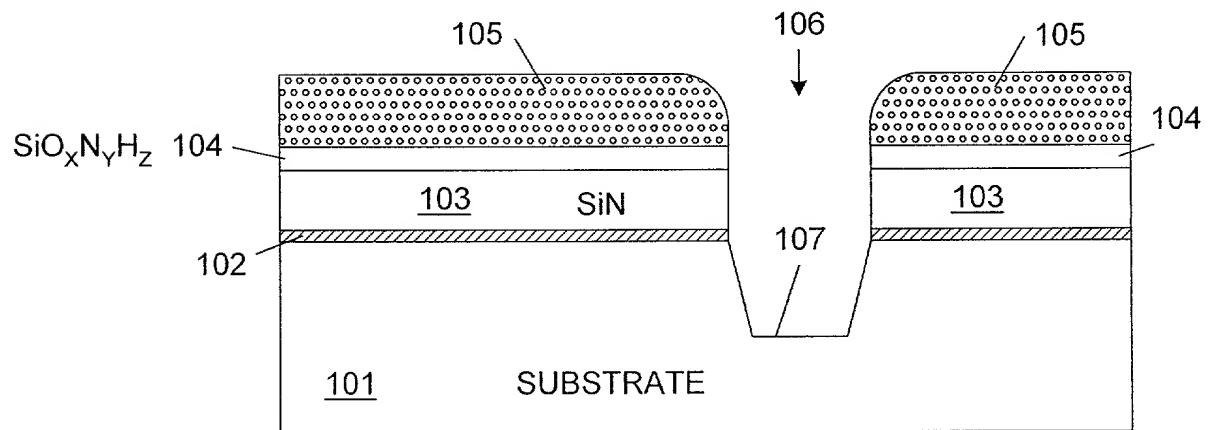


FIG. 3

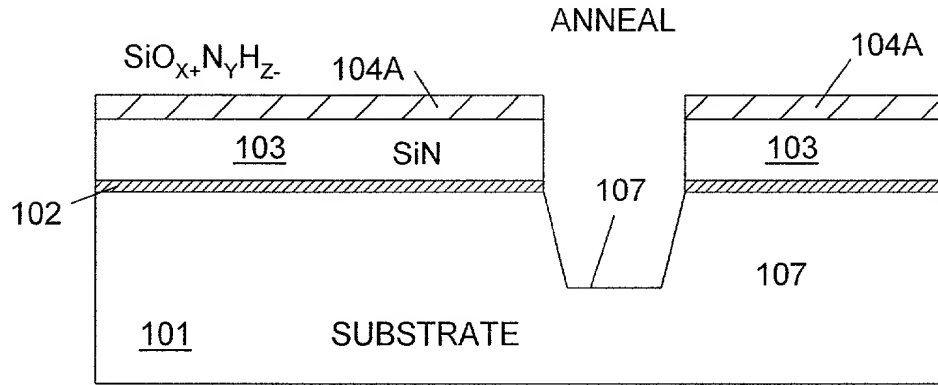


FIG. 4

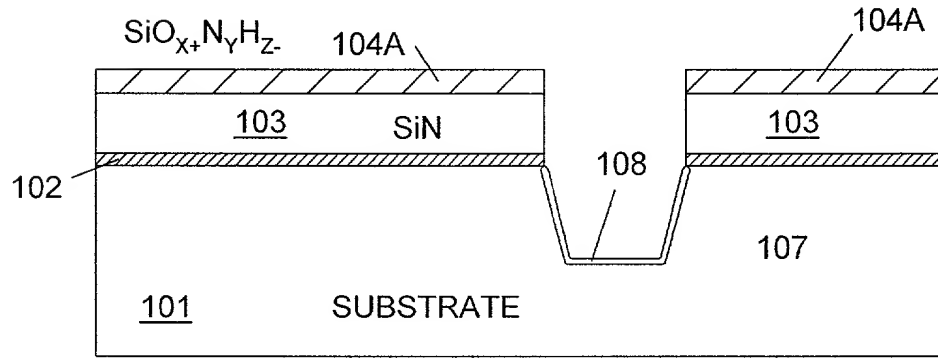


FIG. 5

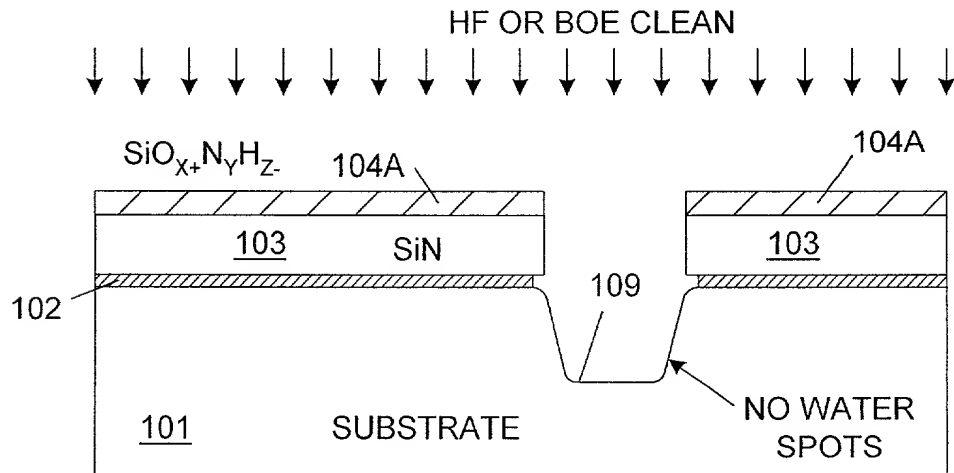


FIG. 6

[illegible]

A cross-sectional view of a substrate 101. A trench 110 is formed in the substrate. A layer 102 is deposited on the top surface of the substrate. A layer 103A is deposited on top of layer 102. A CMP process is indicated by downward arrows, showing the removal of layer 103A and the planarization of layer 102. The trench 110 is shown with a bottom surface 111A.

FIG. 9